## Electronics plans

G. Tejeda Muñoz MuonID México Meeting December 15, 2022



- Transformative **discovery in science** is driven by **innovation in technology**. This mean that our boldest undertakinkgs in particle physics **have at their foundation** <u>precision</u> <u>instrumentation</u>.

- We are firmly conviced that to reveal the profound connections underlying everything we see from the smallest scales to largest distance of the universe, to understand its fundamental constituents, and **to reveal what is still unknow**, **we must invent**, **develop and deploy advanced instrumentation**.



## Introduction

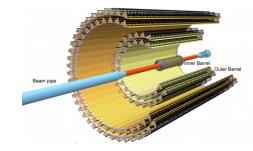
• ACORDE



• TPC



• ITS Upgrade



## • BELLE II (LABM)





FDD

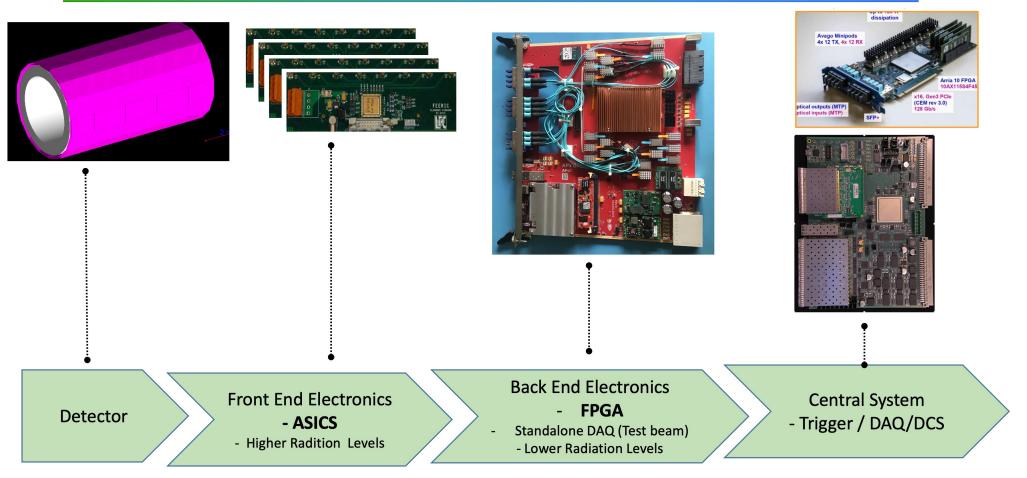
CTP





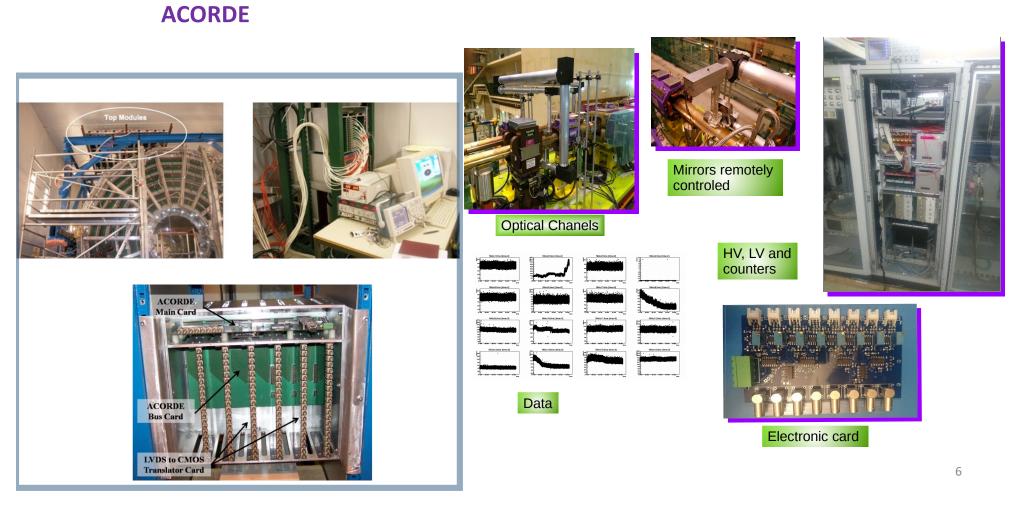


#### Introduction (Associated Electronics to High Energy Experiment)



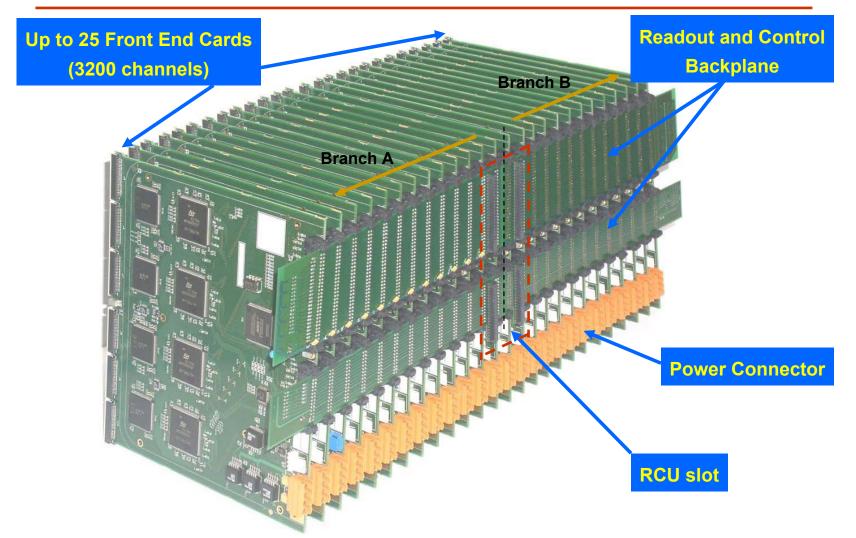
# Electronics in the detector

- FEE (depend on detector type)
- ReadOut
- DAQ system communication
- TRIGGER system communication
- Debugging communication
- Power Supply
- Cabling
- Cooling
- DCS interfce



LABM

## **Readout Backplane – example of readout partition**



## RPC FEE



### First proto

2017 proof of principle for <u>CMS-MUON-TDR-016</u>

2 PetiROC2A + FPGA Cyclone II + ETHERNET directly on strip PCB (50 cm)

#### Feb V0 2018 First FEB (Conf. note) 1 PetiROC2A +

MEZZANINE with FPGA Cyclone II + ETHERNET



#### ote) Feb V1 2019 FEB without mezzanine 2 PetiROC2B

+ FPGA Cyclone V + ETHERNET



Feb V2 2021 Non-rad hard for iRPC Demo

6 PETIROC2C + 3 FPGA Cyclone V + Optical GBT



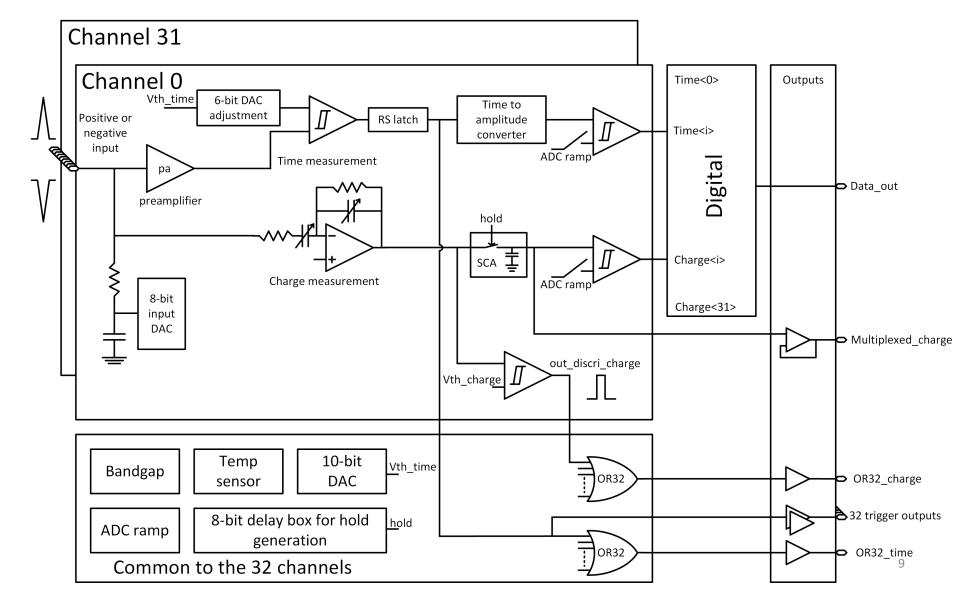
#### Feb V3 $\rightarrow$ 2023 Rad hard final

6 PETIROC2C + 3 FPGA PolarFire + Optical GBT

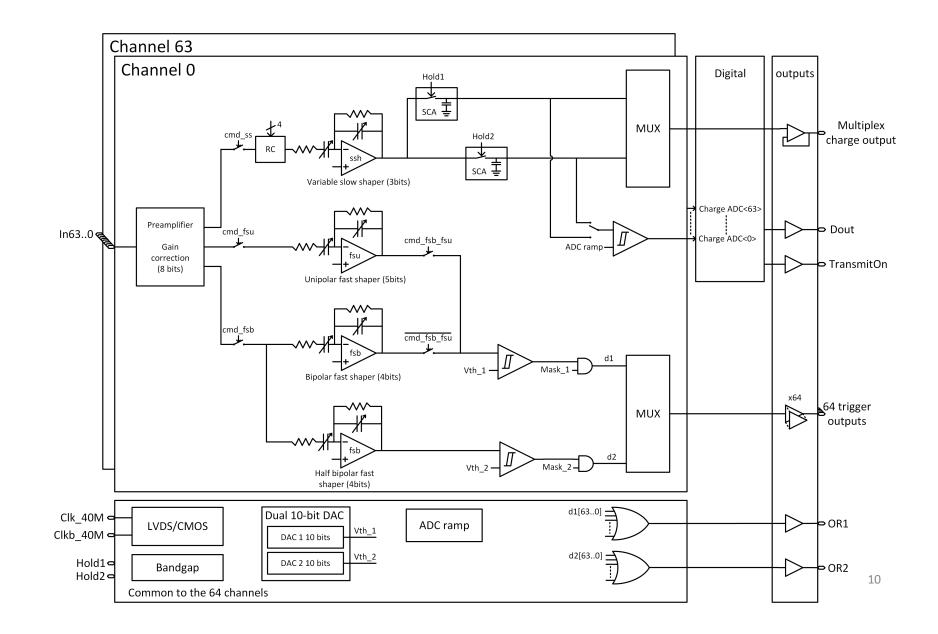








# Petiroc 2C (RPC)



## Channels distributions example

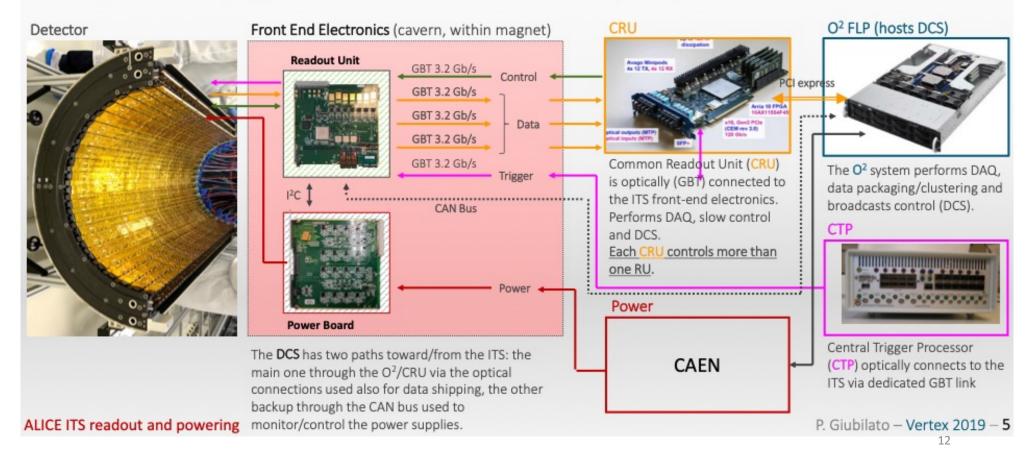
## • 13500 Channels

RPC:

422 PETIROC chips 104 FEE cards with 4 chips (128Ch/card) 13 CRU with 8 FEE connected PMT or SiPM:211 MAROC chips53 FEE cards with 4 chips (256 Ch/card)7 CRU with 8 FEE connected

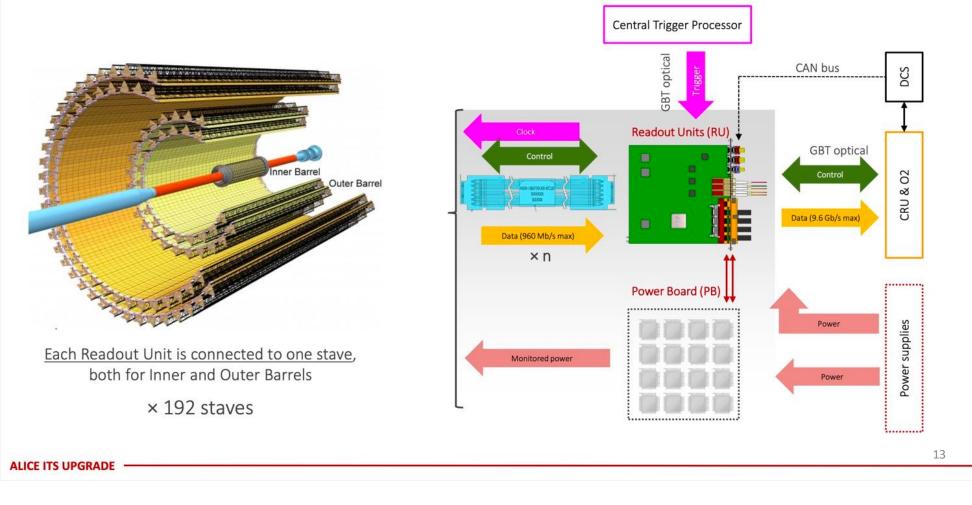
Equivalent for PicoTDC.

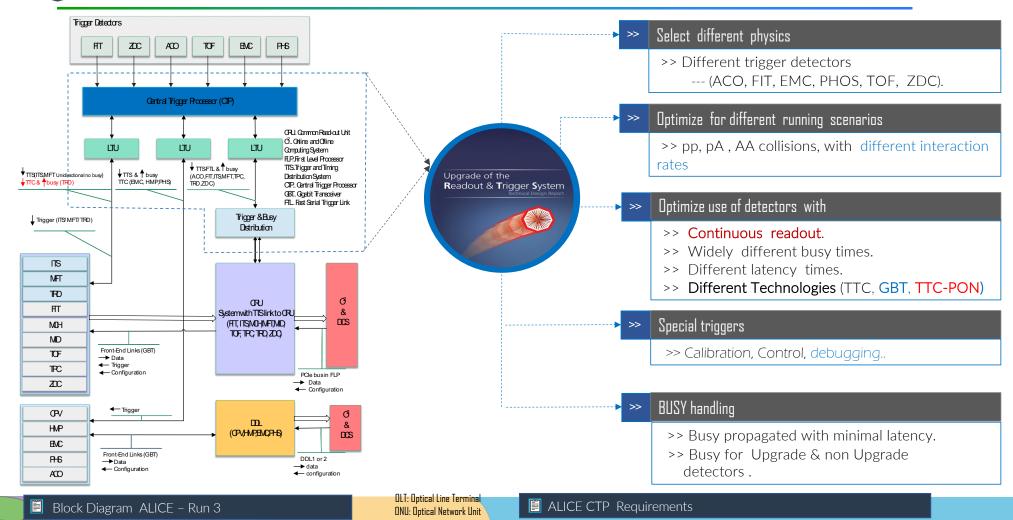
- The ITS Front End Electronic (FEE) is divided into modular Readout Units (RU), identical for each layer.
- Each readout unit controls an entire stave, including power to the sensors (through custom-made Power Boards).
- The experiment DAQ, Trigger and Control interfaces with the RU only through the Common Readout Unit.



## Specifications – ITS Readout Electronics is organized in Readout Units (RU)

The ITS front-end electronics are divided into **192** modular **Readout Units**, each connected to one ITS stave, and optically interfaced with both the Common Readout Unit (CRU) and the Central Trigger Processor (CTP).

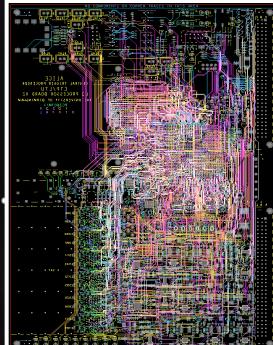




### CTP Requirements for LHC-Run3

## ALICE Trigger board for LHC-Run3





- Kintex-Ultrascale FPGA
- Single universal trigger board (CTP/LTU board).
- Interface between CTP and LTUs is via TTC-PON and optical fan-out unit.
- Will still be based on a VME-type 6u board (VME for power only).
- PCB design

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- \* 20 Layers (I-TERA MT40 material for highspeed digital multilayer)
- All clocks have the same length
- 2GB DDR4 Memory
- 2 Synthesizers
- 20 Optical Links (up to 11 Gbps)

#### Advance Processor board (CMS-Level 1 -- HL- LHC)



## APx- Family card for Phase 2 Trigger: Calorimeter, Correlator Muon.

 Demonstrator for a multi-purpose, customizable, common processing platform, suitable for wide-scale use in CMS back-end trigger subsystems.

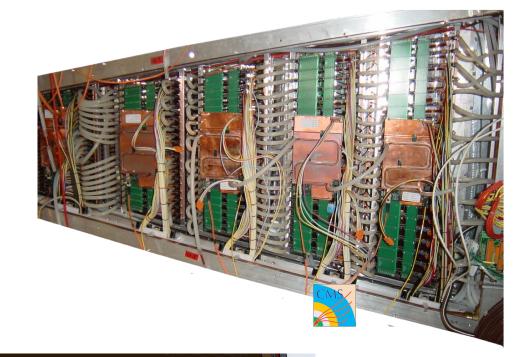
#### Virtex Ultrascale+ FPGA

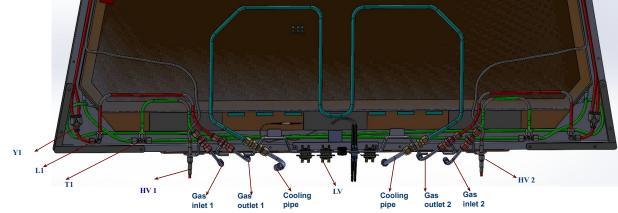
- Flexible and expandible
- Control via ZYNQ SoC (ELM1 Embedded Linx Mezznine)
- Based on ATCA standard
- PCB design
  \* 20 Layers (I-TERA MT40 material for high-speed digital multilayer)
- ~ 100 Rx/Tx Optical links (28 Gbps)
- 4 Synthesizers
- 2 Retimers Chips
- 10GbE ELM connection supported via SFP

## cooling









RPC gas and cooling

## Electronic system tasks

- Design of the FEE for RPCs, PMTs or SiPM.
- Design of the Read Out Unit for the FEE.
- Design of the DCS and electronics communications.
- Design of the trigger and control modules.
- Design of the DAQ system communication.

## Experience in electronics

- Dr. Luis Alberto Perez Moreno
- Guillermo Tejeda Muñoz
- David Regules Medel
- Yael Antonio Vasquez Beltran
- Emigdio Jimenez Dominguez
- Omar Mancilla Martinez

Thank You